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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

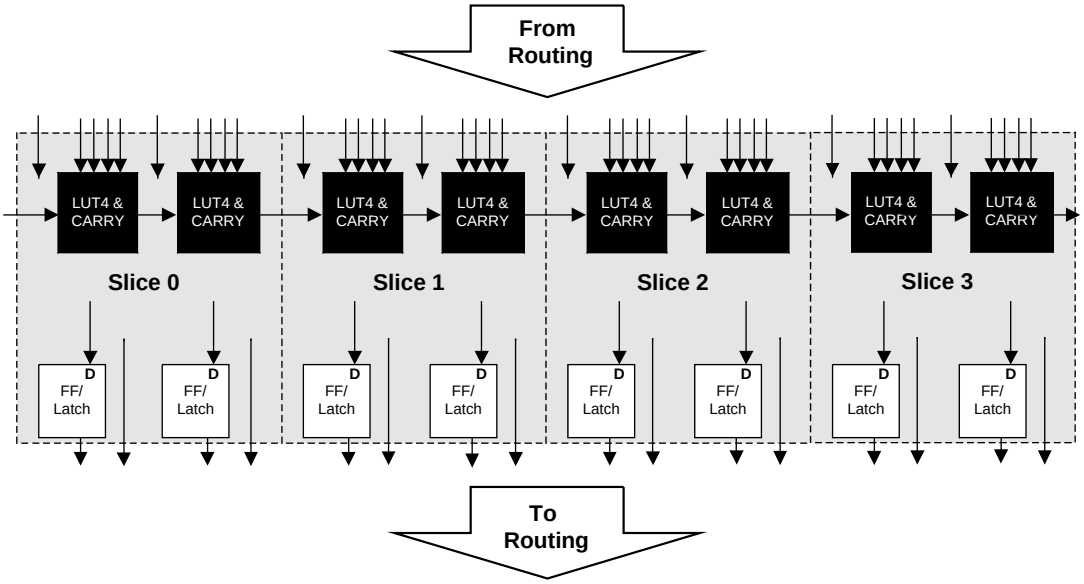
Details	
Product Status	Obsolete
Number of LABs/CLBs	20000
Number of Logic Elements/Cells	80000
Total RAM Bits	5816320
Number of I/O	904
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	1704-BCBGA, FCBGA
Supplier Device Package	1704-CFCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga80e-5fc1704i

PFU Blocks

The core of the LatticeSC devices consists of PFU blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-2. All the interconnections to and from PFU blocks are from routing. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-2. PFU Diagram

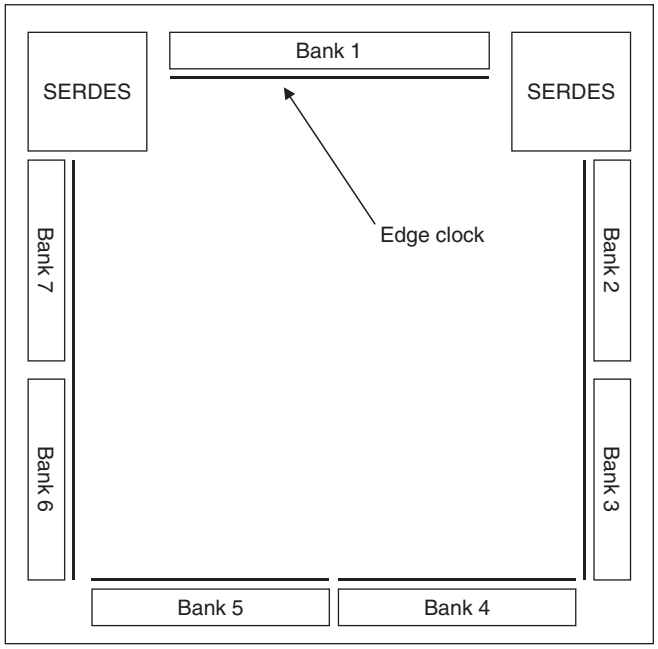


Slice

Each slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to implement 5, 6, 7 and 8 Input LUTs (LUT5, LUT6, LUT7 and LUT8). There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-3 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge/level clocks.

There are 14 input signals: 13 signals from routing and one from the carry-chain (from adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to adjacent PFU). Table 2-1 lists the signals associated with each slice.

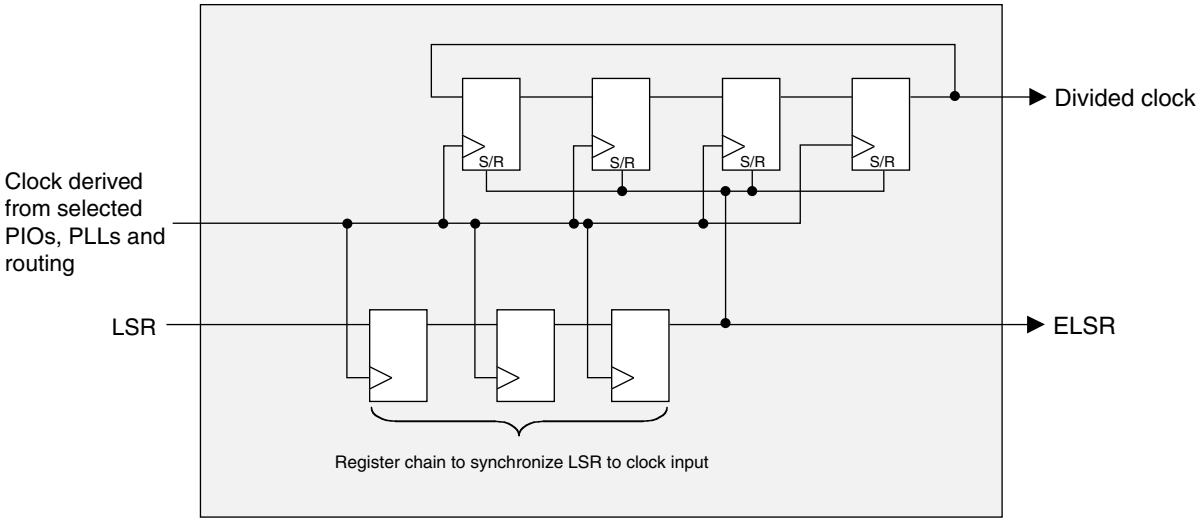
Figure 2-7. Edge Clock Resources



Precision Clock Divider

Each set of edge clocks has four high-speed dividers associated with it. These are intended for generating a slower speed system clock from the high-speed edge clock. The block operates in a DIV2 or DIV4 mode and maintains a known phase relationship between the divided down clock and high-speed clock based on the release of its reset signal. The clock dividers can be fed from selected PIOs, PLLs and routing. The clock divider outputs serve as primary clock sources. This circuit also generates an edge local set/reset (ELSR) signal which is fed to the PIOs via the edge clock network and is used for the rest of the I/O gearing logic.

Figure 2-8. Clock Divider Circuit



Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is

toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-9 illustrates the DCS Block diagram.

Figure 2-9. DCS Block Diagram

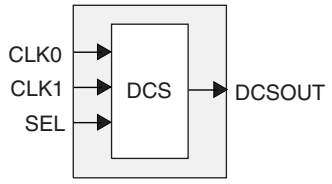
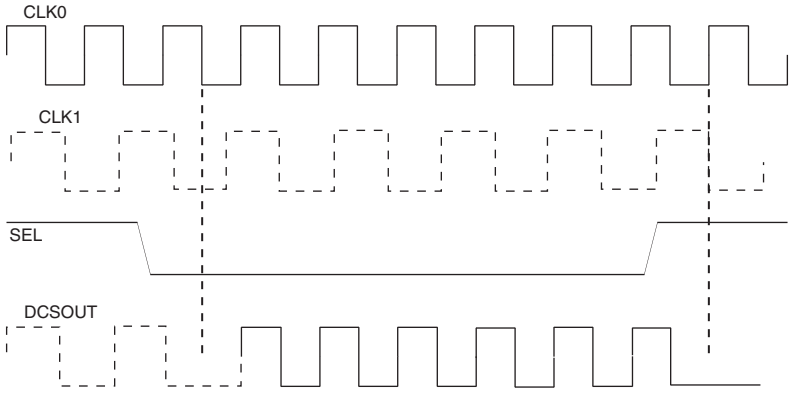


Figure 2-10 shows timing waveforms for one of the DCS operating modes. The DCS block can be programmed to other modes. For more information on the DCS, please see details of additional technical documentation at the end of this data sheet.

Figure 2-10. DCS Waveforms



Clock Boosting

There are programmable delays available in the clock signal paths in the PFU, PIC and EBR blocks. These allow setup and clock-to-output times to be traded to meet critical timing without slowing the system clock. If this feature is enabled then the design tool automatically uses these delays to improve timing performance.

Global Set/Reset

There is a global set/reset (GSR) network on the device that is distributed to all FFs, PLLs, DLLs and other blocks on the device. This GSR network can operate in two modes:

a) asynchronous - no clock is required to get into or out of the reset state.

b) synchronous - The global GSR net is synchronized to a user selected clock. In this mode it continues to be asynchronous to get into the reset state, but is synchronous to get out of the reset state. This allows all registers on the device to become operational in the same clock period. The synchronous GSR goes out of reset in two cycles from the clock edge where the setup time of the FF was met (not from the GSR being released).

sysCLOCK Phase Locked Loops (PLLs)

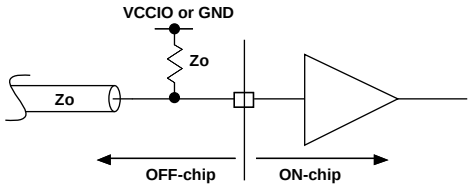
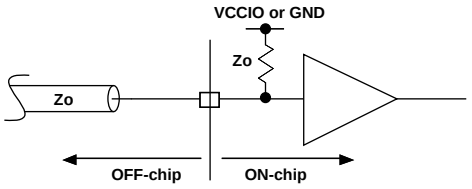
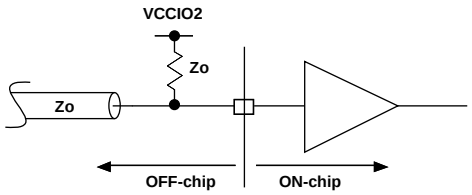
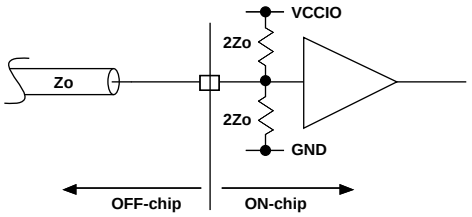
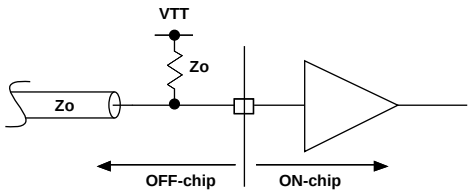
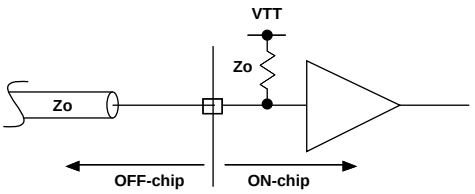
The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider and two clock output dividers. The input divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal.

Single Ended Inputs: The SC devices support a number of different termination schemes for single ended inputs:

- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to V_{TT}

Figure 2-28 shows the single ended input schemes that are supported. The nominal values of the termination resistors are shown in Table 2-9.

Figure 2-28. Input Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Parallel termination to to V_{CCIO}, or parallel to GND receiving end		
Parallel termination to $V_{CCIO}/2$ receiving end		
Parallel termination to V_{TT} at receiving end		

In many situations designers can chose whether to use Thevenin or parallel to V_{TT} termination. The Thevenin approach has the benefit of not requiring a termination voltage to be applied to the device. The parallel to V_{TT} approach consumes less power.

VTT Termination Resources

Each I/O bank, except bank 1, has a number of V_{TT} pins that must be connected if V_{TT} is used. Note V_{TT} pins can sink or source current and the power supply they are connected to must be able to handle the relatively high currents associated with the termination circuits. Note: V_{TT} is not available in all package styles.

On-chip parallel termination to V_{TT} is supported at the receiving end only. On-chip parallel output termination to V_{TT} is not supported.

The V_{TT} internal bus is also connected to the internal V_{CMT} node. Thus in one bank designers can implement either V_{TT} termination or V_{CMT} termination for differential inputs.

DDRII/RLDRAMII Termination Support

The DDR II memory and RLDRAMII (in Bidirection Data mode) standards require that the on-chip termination to V_{TT} be turned on when a pin is an input and off when the pin is an output. The LatticeSC devices contain the required circuitry to support this behavior. For additional detail refer to technical information at the end of the data sheet.

this allows for easy integration with the rest of the system. These capabilities make the LatticeSC ideal for many multiple power supply and hot-swap applications. The maximum current during hot socketing is 4mA. See Hot Socketing Specifications in Chapter 3 of this data sheet.

Power-Up Requirements

To prevent high power supply and input pin currents, each VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies must have a monotonic ramp up time of 75 ms or less to reach its minimum operating voltage. Apart from VCC and VCC12, which have an additional requirement, and VCCIO and VCCAUX, which also have an additional requirement, the VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies can ramp up in any order, with no restriction on the time between them. However, the ramp time for each must be 75 ms or less. Configuration of the device will not proceed until the last power supply has reached its minimum operating voltage.

Additional Requirement for VCC and VCC12:
VCC12 must always be higher than VCC. This condition must be maintained at ALL times, including during power-up and power-down. Note that for 1.2V only operation, it is advisable to source both of these supplies from the same power supply.

Additional Requirement for VCCIO and VCCAUX:
If any VCCIOs are 1.2/1.5/1.8V, then VCCAUX MUST be applied before them. If any VCCIO is 1.2/1.5/1.8V and is powered up before VCCAUX, then when VCCAUX is powered up, it may drag VCCIO up with it as it crosses through the VCCIO value. (Note: If the VCCIO supply is capable of sinking current, as well as the more usual sourcing capability, this behavior is eliminated. However, the amount of current that the supply needs to sink is unknown and is likely to be in the hundreds of milliamps range).

Power-Down Requirements

To prevent high power supply and input pin currents, power must be removed monotonically from either VCC or VCCAUX (and must reach the power-down trip point of 0.5V for VCC, 0.95V for VCCAUX) before power is removed monotonically from VCC12, any of the VCCIOs, or VCCJ. Note that VCC12 can be removed at the same time as VCC, but it cannot be removed earlier. In many applications, VCC and VCC12 will be sourced from the same power supply and so will be removed together. For systems where disturbance of the user pins is a don't care condition, the power supplies can be removed in any order as long as they power down monotonically within 200ms of each other.

Additionally, if any banks have VCCIO=3.3V nominal (potentially banks 1, 4, 5) then VCCIO for those banks must not be lower than VCCAUX during power-down. The normal variation in ramp-up times of power supplies and voltage regulators is not a concern here.

Note: The SERDES power supplies are NOT included in these requirements and have no specific sequencing requirements. However, when using the SERDES with VDDIB or VDDOB that is greater than 1.2V (1.5V nominal for example), the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in the ramp-up times of power supplies and voltage regulators is not a concern here.

SERDES Power Supply Sequencing Requirements

When using the SERDES with 1.5V VDDIB or VDDOB supplies, the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and the 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in ramp-up times of power supples and voltage regulators is not a concern.

Additional Requirement for SERDES Power Supply
All VCC12 pins need to be connected on all devices independent of functionality used on the device. This analog supply is used by both the RX and TX portions of the SERDES and is used to control the core SERDES logic regardless of the SERDES being used in the design. VDDIB and VDDOB are used as supplies for the terminations on the CML input and output buffers. If a particular channel is not used, these can be UNCONNECTED (floating).

PURESPEED I/O Recommended Operating Conditions

Standard	V_{CCIO} (V)			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 33	3.135	3.3	3.465	—	—	—
LVCMOS 25	2.375	2.5	2.625	—	—	—
LVCMOS 18	1.71	1.8	1.89	—	—	—
LVCMOS 15	1.425	1.5	1.575	—	—	—
LVCMOS 12	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.465	—	—	—
PCI33	3.135	3.3	3.465	—	—	—
PCIX33	3.135	3.3	3.465	—	—	—
PCIX15	1.425	1.5	1.575	$0.49V_{CCIO}$	$0.5V_{CCIO}$	$0.51V_{CCIO}$
AGP1X33	3.135	3.3	3.465	—	—	—
AGP2X33	3.135	3.3	3.465	$0.39V_{CCIO}$	$0.4V_{CCIO}$	$0.41V_{CCIO}$
SSTL18_I, II[3]	1.71	1.8	1.89	0.833	0.9	0.969
SSTL25_I, II[3]	2.375	2.5	2.625	1.15	1.25	1.35
SSTL33_I, II[3]	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15_I, II[3]	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15_III[1, 3] and IV[1, 3]	1.425	1.5	1.575	0.68	0.9	0.9
HSTL 18_I[3], II[3]	1.71	1.8	1.89	0.816	0.9	1.08
HSTL 18_ III[1, 3], IV[1, 3]	1.71	1.8	1.89	0.816	1.08	1.08
GTL12[1, 3], GTLPLUS15[1, 3]	—	—	—	0.882	1.0	1.122
LVDS	—	—	—	—	—	—
Mini-LVDS	—	—	—	—	—	—
RSDS	—	—	—	—	—	—
LVPECL33 (outputs)[2]	3.135	3.3	3.465	—	—	—
LVPECL33 (inputs)[2, 4]	—	≤ 2.5	—	—	—	—
BLVDS25[2, 3]	2.375	2.5	2.625	—	—	—
MLVDS25[2, 3]	2.375	2.5	2.625	—	—	—
SSTL18D_I[3], II[3]	1.71	1.8	1.89	—	—	—
SSTL25D_I[3], II[3]	2.375	2.5	2.625	—	—	—
SSTL33D_I[3], II[3]	3.135	3.3	3.465	—	—	—
HSTL15D_I[3], II[3]	1.425	1.5	1.575	—	—	—
HSTL18D_I[3], II[3]	1.71	1.8	1.89	—	—	—

1. Input only.
2. Inputs on chip. Outputs are implemented with the addition of external resisters.
3. Input for this standard does not depend on the value of V_{CCIO}.
4. Inputs for this standard cannot be in 3.3V VCCIO banks (≤ 2.5V only).

LatticeSC/M Family Timing Adders

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Input Adjusters								
LVDS	LVDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
RSDS	RSDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
BLVDS25	BLVDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
MLVDS25	MLVDS	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
LVPECL33	LVPECL	-0.031	-0.031	-0.011	-0.011	0.009	0.009	ns
HSTL18_I	HSTL_18 class I	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL18_II	HSTL_18 class II	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL18_III	HSTL_18 class III	-0.016	-0.018	0.008	0.003	0.032	0.023	ns
HSTL18_IV	HSTL_18 class IV	-0.016	-0.018	0.008	0.003	0.032	0.023	ns
HSTL18D_I	Differential HSTL 18 class I	0.006	0.001	0.029	0.024	0.052	0.046	ns
HSTL18D_II	Differential HSTL 18 class II	0.006	0.001	0.029	0.024	0.052	0.046	ns
HSTL15_I	HSTL_15 class I	-0.005	-0.016	0.026	-0.001	0.057	0.014	ns
HSTL15_II	HSTL_15 class II	-0.005	-0.016	0.026	-0.001	0.057	0.014	ns
HSTL15_III	HSTL_15 class III	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL15_IV	HSTL_15 class IV	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
HSTL15D_I	Differential HSTL 15 class I	-0.021	-0.022	0.001	-0.009	0.022	0.003	ns
HSTL15D_II	Differential HSTL 15 class II	-0.021	-0.022	0.001	-0.009	0.022	0.003	ns
SSTL33_I	SSTL_3 class I	-0.036	-0.061	-0.181	-0.313	-0.326	-0.565	ns
SSTL33_II	SSTL_3 class II	-0.036	-0.061	-0.181	-0.313	-0.326	-0.565	ns
SSTL33D_I	Differential SSTL_3 class I	0.012	0.012	0.034	0.028	0.055	0.043	ns
SSTL33D_II	Differential SSTL_3 class II	0.012	0.012	0.034	0.028	0.055	0.043	ns
SSTL25_I	SSTL_2 class I	0.003	-0.008	0.03	0.011	0.058	0.03	ns
SSTL25_II	SSTL_2 class II	0.003	-0.008	0.03	0.011	0.058	0.03	ns
SSTL25D_I	Differential SSTL_2 class I	0.006	0	0.031	0.023	0.056	0.046	ns
SSTL25D_II	Differential SSTL_2 class II	0.006	0	0.031	0.023	0.056	0.046	ns
SSTL18_I	SSTL_18 class I	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
SSTL18_II	SSTL_18 class II	-0.013	-0.015	0.015	0.007	0.042	0.029	ns
SSTL18D_I	Differential SSTL_18 class I	0.006	0.001	0.029	0.024	0.052	0.046	ns
SSTL18D_II	Differential SSTL_18 class II	0.006	0.001	0.029	0.024	0.052	0.046	ns
LVTTL33	LVTTL	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
LVCMOS33	LVCMOS 3.3	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
LVCMOS25	LVCMOS 2.5	0	0	0	0	0	0	ns
LVCMOS18	LVCMOS 1.8	-0.068	-0.068	-0.087	-0.087	-0.105	-0.105	ns
LVCMOS15	LVCMOS 1.5	-0.131	-0.131	-0.186	-0.186	-0.241	-0.241	ns
LVCMOS12	LVCMOS 1.2	-0.238	-0.238	-0.364	-0.364	-0.49	-0.49	ns
PCI33	PCI	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
PCIX33	PCI-X 3.3	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
PCIX15	PCI-X 1.5	-0.005	-0.016	0.026	-0.001	0.057	0.014	ns
AGP1X33	AGP-1X 3.3	0.034	0.034	-0.05	-0.05	-0.134	-0.134	ns
AGP2X33	AGP-2X	-0.036	-0.061	-0.181	-0.313	-0.326	-0.565	ns

LatticeSC/M Internal Timing Parameters[1] (Continued)

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Parameter	Symbol	Description	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
EBR Timing									
t_{CO_EBR}	CK_Q_DEL	Clock (Read) to output from Address or Data	—	1.900	—	2.116	—	2.335	ns
t_{COO_EBR}	CK_Q_DEL	Clock (Write) to output from EBR output Register	0.390	—	0.444	—	0.498	—	ns
t_{SUDATA_EBR}	D_CK_SET	Setup Data to EBR Memory (Write clk)	-0.173	—	-0.192	—	-0.210	—	ns
t_{HDATA_EBR}	D_CK_HLD	Hold Data to EBR Memory (Write clk)	0.276	—	0.305	—	0.335	—	ns
t_{SUADDR_EBR}	A_CK_SET	Setup Address to EBR Memory (Write clk)	-0.165	—	-0.182	—	-0.200	—	ns
t_{HADDR_EBR}	A_CK_HLD	Hold Address to EBR Memory (Write clk)	0.269	—	0.298	—	0.327	—	ns
t_{SUWREN_EBR}	CE_CK_SET	Setup Write/Read Enable to EBR Memory (Write/Read clk)	0.225	—	0.226	—	0.226	—	ns
t_{HWREN_EBR}	CE_CK_HLD	Hold Write/Read Enable to EBR Memory (write/read clk)	0.073	—	0.095	—	0.116	—	ns
t_{SUCE_EBR}	CS_CK_SET	Clock Enable Setup Time to EBR Output Register (Read clk)	0.261	—	0.269	—	0.276	—	ns
t_{HCE_EBR}	CS_CK_HLD	Clock Enable Hold Time to EBR Output Register (Read clk)	0.023	—	0.039	—	0.055	—	ns
t_{RSTO_EBR}	RESET_Q_DEL	Reset To Output Delay Time from EBR Output Register (asynchronous)	—	0.589	—	0.673	—	0.757	ns
Cycle Boosting Timing									
t_{DEL1}	DEL1	Cycle boosting delay 1 applies to PIO, PFU, EBR	—	0.480	—	0.524	—	0.570	ns
t_{DEL2}	DEL2	Cycle boosting delay 2 applies to PIO, PFU, EBR	—	0.922	—	1.005	—	1.090	ns
t_{DEL3}	DEL3	Cycle boosting delay 3 applies to PIO, PFU, EBR	—	1.366	—	1.488	—	1.612	ns

1. Complete timing parameters for a user design will be incorporated when running ispLEVER. This is a sampling of the key timing parameters.

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH11	PB47C	4	PCLKT4_6	PB54C	4	PCLKT4_6
AH10	PB47D	4	PCLKC4_6	PB54D	4	PCLKC4_6
AK12	PB49A	4	PCLKT4_0	PB55A	4	PCLKT4_0
AJ12	PB49B	4	PCLKC4_0	PB55B	4	PCLKC4_0
AF14	PB49C	4	VREF2_4	PB55C	4	VREF2_4
AE14	PB49D	4		PB55D	4	
AL11	PB51A	4	PCLKT4_5	PB57A	4	PCLKT4_5
AL10	PB51B	4	PCLKC4_5	PB57B	4	PCLKC4_5
AH9	PB51C	4		PB57C	4	
AH8	PB51D	4		PB57D	4	
AK11	PB52A	4	PCLKT4_3	PB58A	4	PCLKT4_3
AJ11	PB52B	4	PCLKC4_3	PB58B	4	PCLKC4_3
AH7	PB52C	4	PCLKT4_4	PB58C	4	PCLKT4_4
AH6	PB52D	4	PCLKC4_4	PB58D	4	PCLKC4_4
AK8	PB53A	4		PB67A	4	
AJ8	PB53B	4		PB67B	4	
AF11	PB53C	4		PB67C	4	
AD12	PB55A	4		PB69A	4	
AE12	PB55B	4		PB69B	4	
AM6	PB56A	4		PB70A	4	
AM5	PB56B	4		PB70B	4	
AC12	PB56C	4		PB70C	4	
AL6	PB57A	4		PB73A	4	
AL5	PB57B	4		PB73B	4	
AG7	PB59A	4		PB74A	4	
AG8	PB59B	4		PB74B	4	
AK6	PB60A	4		PB75A	4	
AJ6	PB60B	4		PB75B	4	
AF10	PB60C	4		PB75C	4	
AE11	PB60D	4		PB75D	4	
AM4	PB61A	4		PB77A	4	
AM3	PB61B	4		PB77B	4	
AH5	PB63A	4		PB78A	4	
AH4	PB63B	4		PB78B	4	
AK5	PB64A	4		PB79A	4	
AJ5	PB64B	4		PB79B	4	
AF8	PB64C	4		PB79C	4	
AF7	PB64D	4		PB79D	4	
AL4	PB65A	4		PB81A	4	
AL3	PB65B	4		PB81B	4	
AG5	PB65C	4		PB81C	4	
AF6	PB65D	4		PB81D	4	
AK3	PB67A	4		PB82A	4	
AJ3	PB67B	4		PB82B	4	
AE10	PB67C	4	VREF1_4	PB82C	4	VREF1_4
AD10	PB67D	4		PB82D	4	
AL2	PB68A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D	PB83A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AK2	PB68B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB83B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AE9	PB68C	4		PB83C	4	
AE8	PB68D	4		PB83D	4	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P10	GND	-		GND	-	
P13	GND	-		GND	-	
P15	GND	-		GND	-	
P18	GND	-		GND	-	
P20	GND	-		GND	-	
P24	GND	-		GND	-	
R12	GND	-		GND	-	
R14	GND	-		GND	-	
R16	GND	-		GND	-	
R17	GND	-		GND	-	
R19	GND	-		GND	-	
R21	GND	-		GND	-	
R26	GND	-		GND	-	
R6	GND	-		GND	-	
T15	GND	-		GND	-	
T18	GND	-		GND	-	
T30	GND	-		GND	-	
T4	GND	-		GND	-	
U15	GND	-		GND	-	
U18	GND	-		GND	-	
U29	GND	-		GND	-	
U3	GND	-		GND	-	
V12	GND	-		GND	-	
V14	GND	-		GND	-	
V16	GND	-		GND	-	
V17	GND	-		GND	-	
V19	GND	-		GND	-	
V21	GND	-		GND	-	
V27	GND	-		GND	-	
V7	GND	-		GND	-	
W13	GND	-		GND	-	
W15	GND	-		GND	-	
W18	GND	-		GND	-	
W20	GND	-		GND	-	
W23	GND	-		GND	-	
W9	GND	-		GND	-	
Y12	GND	-		GND	-	
Y14	GND	-		GND	-	
Y19	GND	-		GND	-	
Y21	GND	-		GND	-	
Y30	GND	-		GND	-	
Y4	GND	-		GND	-	
N13	VCC	-		VCC	-	
N15	VCC	-		VCC	-	
N16	VCC	-		VCC	-	
N17	VCC	-		VCC	-	
N18	VCC	-		VCC	-	
N20	VCC	-		VCC	-	
P14	VCC	-		VCC	-	
P16	VCC	-		VCC	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C32	VCC12	-		VCC12	-	
E34	NC	-		PL22A	7	
F34	NC	-		PL22B	7	
F33	NC	-		PL24A	7	
G33	NC	-		PL24B	7	
K30	NC	-		PL25A	7	
L30	NC	-		PL25B	7	
G34	NC	-		PL26A	7	
H34	NC	-		PL26B	7	
M32	NC	-		PL39A	7	
N32	NC	-		PL39B	7	
P28	NC	-		PL39C	7	
R28	NC	-		PL39D	7	
J34	NC	-		PL41A	7	
K34	NC	-		PL41B	7	
P30	NC	-		PL41C	7	
R30	NC	-		PL41D	7	
W34	NC	-		PL59A	6	
Y34	NC	-		PL59B	6	
W32	NC	-		PL61A	6	
Y32	NC	-		PL61B	6	
AA34	NC	-		PL64A	6	
AB34	NC	-		PL64B	6	
AC34	NC	-		PL67A	6	
AD34	NC	-		PL67B	6	
Y30	NC	-		PL68A	6	
AA30	NC	-		PL68B	6	
AB33	NC	-		PL69A	6	
AC33	NC	-		PL69B	6	
AC2	NC	-		PR69B	3	
AB2	NC	-		PR69A	3	
AA5	NC	-		PR68B	3	
Y5	NC	-		PR68A	3	
AD1	NC	-		PR67B	3	
AC1	NC	-		PR67A	3	
AB1	NC	-		PR64B	3	
AA1	NC	-		PR64A	3	
Y3	NC	-		PR61B	3	
W3	NC	-		PR61A	3	
Y1	NC	-		PR59B	3	
W1	NC	-		PR59A	3	
R5	NC	-		PR41D	2	
P5	NC	-		PR41C	2	
K1	NC	-		PR41B	2	
J1	NC	-		PR41A	2	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
G27	A_REFCLKP_L	-	
H27	A_REFCLKN_L	-	
H25	VCC12	-	
H26	RESP_ULC	-	
B33	RESETN	1	
C34	TSALLN	1	
D34	DONE	1	
C33	INITN	1	
J27	M0	1	
K27	M1	1	
M26	M2	1	
L26	M3	1	
F30	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
G30	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
H28	PL15C	7	
J28	PL15D	7	
F31	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
G31	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
N25	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
P25	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
D33	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
E33	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
H29	PL18C	7	
J29	PL18D	7	VREF2_7
F32	PL19A	7	
G32	PL19B	7	
P26	PL19C	7	
N26	PL19D	7	
H30	PL26A	7	
J30	PL26B	7	
L28	PL26C	7	
M28	PL26D	7	
J31	PL43A	7	
K31	PL43B	7	
L27	PL43C	7	VREF1_7
M27	PL43D	7	DIFFR_7
J32	PL45A	7	
K32	PL45B	7	
L29	PL45C	7	
M29	PL45D	7	
H33	PL47A	7	
J33	PL47B	7	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AJ34	PL98A	6	
AK34	PL98B	6	
AB27	PL98C	6	
AC27	PL98D	6	
AF33	PL99A	6	
AG33	PL99B	6	
AC29	PL99C	6	
AD29	PL99D	6	
AE31	PL103A	6	
AF31	PL103B	6	
AF30	PL103C	6	
AF29	PL103D	6	
AH33	PL104A	6	
AJ33	PL104B	6	
AC28	PL104C	6	
AD28	PL104D	6	
AH32	PL107A	6	
AJ32	PL107B	6	
AD27	PL107C	6	
AE27	PL107D	6	VREF2_6
AG34	PL109A	6	
AH34	PL109B	6	
AC26	PL109C	6	
AB26	PL109D	6	
AK33	PL112A	6	
AL33	PL112B	6	
AG30	PL112C	6	
AH30	PL112D	6	
AL34	PL115A	6	
AM34	PL115B	6	
AJ30	PL115C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AK30	PL115D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AJ31	PL116A	6	
AH31	PL116B	6	
AD26	PL116C	6	
AD25	PL116D	6	
AL32	PL117A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AL31	PL117B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AG29	PL117C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AG28	PL117D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AF28	XRES	-	
AF27	TEMP	6	
AM33	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AN8	PB123B	4	
AG11	PB123C	4	
AG10	PB123D	4	
AP7	PB125A	4	
AP6	PB125B	4	
AG13	PB125C	4	
AG12	PB125D	4	
AN7	PB127A	4	
AN6	PB127B	4	
AK9	PB127C	4	
AK8	PB127D	4	
AP5	PB129A	4	
AP4	PB129B	4	
AD11	PB129C	4	
AE11	PB129D	4	
AM7	PB131A	4	
AM6	PB131B	4	
AJ9	PB131C	4	
AJ8	PB131D	4	
AP3	PB133A	4	
AN3	PB133B	4	
AF10	PB133C	4	
AE10	PB133D	4	
AL7	PB135A	4	
AL6	PB135B	4	
AK7	PB135C	4	
AK6	PB135D	4	
AN5	PB138A	4	
AN4	PB138B	4	
AH9	PB138C	4	VREF1_4
AH8	PB138D	4	
AM3	PB139A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AM4	PB139B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AG9	PB139C	4	
AG8	PB139D	4	
AN2	PB141A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AM2	PB141B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AJ6	PB141C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AH6	PB141D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AF7	PROBE_VCC	-	
AF8	PROBE_GND	-	
AG7	PR117D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AG6	PR117C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
BB12	PB88B	4		PB102B	4	
AM17	PB88C	4		PB102C	4	
AL17	PB88D	4		PB102D	4	
AW14	PB89A	4		PB103A	4	
AW13	PB89B	4		PB103B	4	
AP16	PB89C	4		PB103C	4	
AN16	PB89D	4		PB103D	4	
BA13	PB91A	4		PB105A	4	
BA12	PB91B	4		PB105B	4	
AU13	PB91C	4		PB105C	4	
AU12	PB91D	4		PB105D	4	
BB11	PB92A	4		PB106A	4	
BB10	PB92B	4		PB106B	4	
AP15	PB92C	4		PB106C	4	
AN15	PB92D	4		PB106D	4	
AV13	PB93A	4		PB107A	4	
AV12	PB93B	4		PB107B	4	
AT13	PB93C	4		PB107C	4	
AT12	PB93D	4		PB107D	4	
BA11	PB95A	4		PB109A	4	
BA10	PB95B	4		PB109B	4	
AR13	PB95C	4		PB109C	4	
AR12	PB95D	4		PB109D	4	
AY11	PB96A	4		PB110A	4	
AY10	PB96B	4		PB110B	4	
AP14	PB96C	4		PB110C	4	
AN14	PB96D	4		PB110D	4	
BB9	PB97A	4		PB111A	4	
BB8	PB97B	4		PB111B	4	
AU11	PB97C	4		PB111C	4	
AU10	PB97D	4		PB111D	4	
AW11	PB99A	4		PB113A	4	
AW10	PB99B	4		PB113B	4	
AJ16	PB99C	4		PB113C	4	
AJ17	PB99D	4		PB113D	4	
BA9	PB100A	4		PB114A	4	
BA8	PB100B	4		PB114B	4	
AM15	PB100C	4		PB114C	4	
AL15	PB100D	4		PB114D	4	
AV11	PB101A	4		PB115A	4	
AV10	PB101B	4		PB115B	4	
AP13	PB101C	4		PB115C	4	
AP12	PB101D	4		PB115D	4	
BB7	PB103A	4		PB117A	4	
BB6	PB103B	4		PB117B	4	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
E37	B_HDINN0_L	-	PCS 361 CH 0 IN N	B_HDINN0_L	-	PCS 361 CH 0 IN N
D37	B_HDINP0_L	-	PCS 361 CH 0 IN P	B_HDINP0_L	-	PCS 361 CH 0 IN P
F34	B_VDDIB0_L	-		B_VDDIB0_L	-	
N29	VCC12	-		VCC12	-	
L30	A_VDDIB3_L	-		A_VDDIB3_L	-	
K31	VCC12	-		VCC12	-	
D38	A_HDINP3_L	-	PCS 360 CH 3 IN P	A_HDINP3_L	-	PCS 360 CH 3 IN P
E38	A_HDINN3_L	-	PCS 360 CH 3 IN N	A_HDINN3_L	-	PCS 360 CH 3 IN N
A37	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
G37	VCC12	-		VCC12	-	
B37	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
L33	A_VDDOB3_L	-		A_VDDOB3_L	-	
B38	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
D41	A_VDDOB2_L	-		A_VDDOB2_L	-	
A38	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
K34	VCC12	-		VCC12	-	
E39	A_HDINN2_L	-	PCS 360 CH 2 IN N	A_HDINN2_L	-	PCS 360 CH 2 IN N
D39	A_HDINP2_L	-	PCS 360 CH 2 IN P	A_HDINP2_L	-	PCS 360 CH 2 IN P
M32	A_VDDIB2_L	-		A_VDDIB2_L	-	
J32	VCC12	-		VCC12	-	
E41	A_VDDIB1_L	-		A_VDDIB1_L	-	
M33	VCC12	-		VCC12	-	
D40	A_HDINP1_L	-	PCS 360 CH 1 IN P	A_HDINP1_L	-	PCS 360 CH 1 IN P
E40	A_HDINN1_L	-	PCS 360 CH 1 IN N	A_HDINN1_L	-	PCS 360 CH 1 IN N
B39	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
B41	VCC12	-		VCC12	-	
A39	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
C41	A_VDDOB1_L	-		A_VDDOB1_L	-	
B40	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
E42	A_VDDOB0_L	-		A_VDDOB0_L	-	
A40	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
F42	VCC12	-		VCC12	-	
D42	A_HDINN0_L	-	PCS 360 CH 0 IN N	A_HDINN0_L	-	PCS 360 CH 0 IN N
C42	A_HDINP0_L	-	PCS 360 CH 0 IN P	A_HDINP0_L	-	PCS 360 CH 0 IN P
H39	A_VDDIB0_L	-		A_VDDIB0_L	-	
F41	VCC12	-		VCC12	-	
P16	VDDAX25_R	-		VDDAX25_R	-	
P27	VDDAX25_L	-		VDDAX25_L	-	
K39	NC	-		PL32A	7	
L39	NC	-		PL32B	7	
M38	NC	-		PL35A	7	
K40	NC	-		PL36A	7	
L40	NC	-		PL36B	7	
N37	NC	-		PL39A	7	
P37	NC	-		PL39B	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AG38	NC	-		PL95A	6	
AH38	NC	-		PL95B	6	
AJ39	NC	-		PL100A	6	
AK39	NC	-		PL100B	6	
AL41	NC	-		PL105A	6	
AM41	NC	-		PL105B	6	
AN40	NC	-		PL108A	6	
AM40	NC	-		PL108B	6	
AM39	NC	-		PL111A	6	
AN39	NC	-		PL111B	6	
AR42	NC	-		PL113A	6	
AT42	NC	-		PL113B	6	
AT1	NC	-		PR113B	3	
AR1	NC	-		PR113A	3	
AN4	NC	-		PR111B	3	
AM4	NC	-		PR111A	3	
AM3	NC	-		PR108B	3	
AN3	NC	-		PR108A	3	
AM2	NC	-		PR105B	3	
AL2	NC	-		PR105A	3	
AK4	NC	-		PR100B	3	
AJ4	NC	-		PR100A	3	
AH5	NC	-		PR95B	3	
AG5	NC	-		PR95A	3	
P6	NC	-		PR39B	2	
N6	NC	-		PR39A	2	
L3	NC	-		PR36B	2	
K3	NC	-		PR36A	2	
M5	NC	-		PR35A	2	
L4	NC	-		PR32B	2	
K4	NC	-		PR32A	2	
A2	GND	-		GND	-	
A41	GND	-		GND	-	
AA20	GND	-		GND	-	
AA23	GND	-		GND	-	
AA3	GND	-		GND	-	
AA39	GND	-		GND	-	
AB20	GND	-		GND	-	
AB23	GND	-		GND	-	
AB4	GND	-		GND	-	
AB40	GND	-		GND	-	
AC17	GND	-		GND	-	
AC19	GND	-		GND	-	
AC21	GND	-		GND	-	
AC22	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB25	VCC	-		VCC	-	
AB26	VCC	-		VCC	-	
AC16	VCC	-		VCC	-	
AC18	VCC	-		VCC	-	
AC20	VCC	-		VCC	-	
AC23	VCC	-		VCC	-	
AC25	VCC	-		VCC	-	
AC27	VCC	-		VCC	-	
AD17	VCC	-		VCC	-	
AD19	VCC	-		VCC	-	
AD21	VCC	-		VCC	-	
AD22	VCC	-		VCC	-	
AD24	VCC	-		VCC	-	
AD26	VCC	-		VCC	-	
AE16	VCC	-		VCC	-	
AE18	VCC	-		VCC	-	
AE20	VCC	-		VCC	-	
AE21	VCC	-		VCC	-	
AE22	VCC	-		VCC	-	
AE23	VCC	-		VCC	-	
AE25	VCC	-		VCC	-	
AE27	VCC	-		VCC	-	
AF17	VCC	-		VCC	-	
AF19	VCC	-		VCC	-	
AF21	VCC	-		VCC	-	
AF22	VCC	-		VCC	-	
AF24	VCC	-		VCC	-	
AF26	VCC	-		VCC	-	
AG18	VCC	-		VCC	-	
AG20	VCC	-		VCC	-	
AG23	VCC	-		VCC	-	
AG25	VCC	-		VCC	-	
T18	VCC	-		VCC	-	
T20	VCC	-		VCC	-	
T23	VCC	-		VCC	-	
T25	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U19	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
U22	VCC	-		VCC	-	
U24	VCC	-		VCC	-	
U26	VCC	-		VCC	-	
V16	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FF1152C	-6	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FF1152C	-5	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FF1704C	-6	Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FF1704C	-5	Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-6FFN1020I[1]	-6	Lead-Free Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-5FFN1020I[1]	-5	Lead-Free Organic fcBGA	1020	IND	40.4
LFSCM3GA40EP1-6FFAN1020I	-6	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-5FFAN1020I	-5	Lead-Free Organic fcBGA Revision 2	1020	IND	40.4
LFSCM3GA40EP1-6FCN1152I[2]	-6	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FCN1152I[2]	-5	Lead-Free Ceramic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	40.4
LFSCM3GA40EP1-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA80E-6FCN1152I[1]	-6	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-5FCN1152I[1]	-5	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSC3GA80E-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	80.1
LFSC3GA80E-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	80.1
LFSC3GA80E-6FCN1704I[1]	-6	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-5FCN1704I[1]	-5	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSC3GA80E-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	80.1
LFSC3GA80E-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA80EP1-6FCN1152I[1]	-6	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FCN1152I[1]	-5	Lead-Free Ceramic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FFN1152I	-6	Lead-Free Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-5FFN1152I	-5	Lead-Free Organic fcBGA	1152	IND	80.1
LFSCM3GA80EP1-6FCN1704I[1]	-6	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FCN1704I[1]	-5	Lead-Free Ceramic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-6FFN1704I	-6	Lead-Free Organic fcBGA	1704	IND	80.1
LFSCM3GA80EP1-5FFN1704I	-5	Lead-Free Organic fcBGA	1704	IND	80.1

1. Converted to organic flip-chip BGA package per PCN #01A-10.